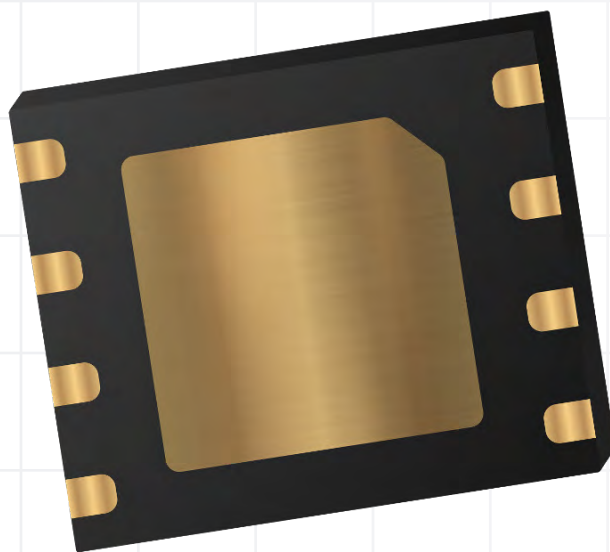


# Dual-Core Capable eUICC SIM with Fallback

Embedded SIM (eSIM) format



# Dual-Core Capable eUICC SIM with Fallback

Embedded SIM Format - MFF2, DFN8

## Product overview

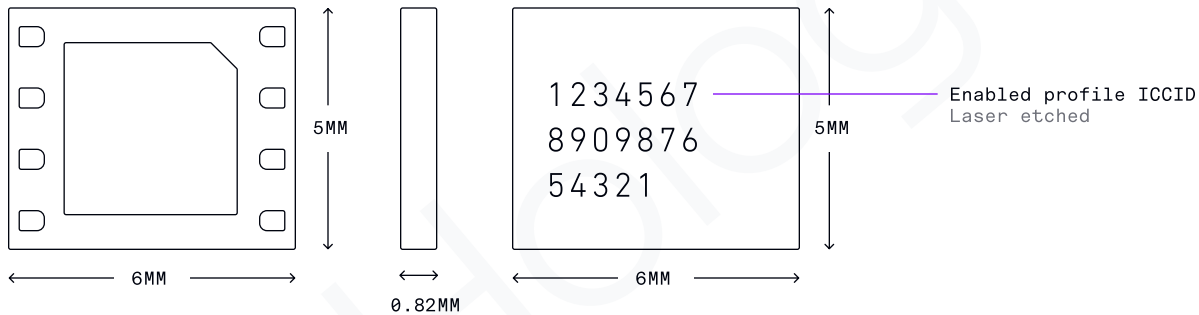
A secure, device-agnostic IoT embedded SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs use an eUICC OS to remotely update coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

## Network availability

Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

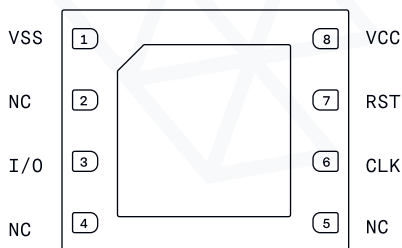
## Mechanical specifications

### Bottom view



## Physical characteristics

### Top view



### Size

MFF2 (DFN8)	Embedded SIM	6 × 5 × 0.82 mm
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## Part numbers

G2-F-DFN8  
US2+-G2-F-DFN8  
US2M-G2-F-DFN8  
CA1-G2-F-DFN8

## Past part numbers

GL2-AFB-MFF2  
GL2-USA2+-AFB-MFF2  
GL2-USA2M-AFB-MFF2

## Multipack labeling

Single SIM: G2-F-DFN8  
250-pack: G2-F-DFN8-250  
2500-pack: G2-F-DFN8-2500

### Pin definitions

1	VSS	Voltage Source Supply
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

## Hardware features

### Chip type

Supplier	Infineon
Chip Code	SLM17ECB800B

### Electrical

Operating Voltage	1.62V to 5.5V
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### Hardware characteristics

Grade	Industrial
Operational Temperature	-40°C to +105°C
Data Retention	10 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	330 KB
Memory (SRAM)	20 KB

### AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 - Smart Cards; UICC-Terminal interface; Physical and logical characteristics  
ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

## Compliance

Chip	 Common Criteria	EAL 4+ PP-0084 (chipset) Certificate: BSI-DSZ-CC-1126-V2-2021
OS		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
		SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
		Card Specification Version 2.3.1 Card Specification Amendments A, B, D & E
Software		Java Card 3 Platform, Classic Edition version 3.0.5
		Release 16
Remote SIM provisioning		SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
Supplier's Declaration of Conformity		Manufactured according to the following standards: <ul style="list-style-type: none"> <li>• RoHS Directive 2011/65/EU</li> <li>• Reach certification</li> <li>• GSMA SAS-UP</li> <li>• ISO 9001:2015</li> <li>• ISO 27001</li> <li>• ISO 14001</li> </ul>